

### REMARKS

In response to the Office Action, claims 9-13, 15-16 and 18-20 have been amended for improved clarity, and claim 14 has been canceled.

Claims 10 and 16 have been rejected under 35 USC 112, second paragraph. Claims 10 and 16 have been amended.

Claims 9, 12-16 and 18-20 have been rejected under 35 USC 102(b) as anticipated by Nishikawa (JP 06097656 A). The rejection is respectfully traversed. The rejection to claim 14 is moot.

Nishikawa uses a metal paste which does not generate shrinkage accompanying sintering in a direction parallel to a piled layer surface (see, for example, paragraph 25 of the Nishikawa translation as disclosing use of “an electric conduction paste”). Therefore, in Nishikawa, there is no dislocation of electrodes and no resulting connection failure. This is in contrast to the invention, where a structured foil is used to integrate an electrical component. Use of the metal foil means shrinkage does not occur in such a film. The metal foil also has the advantage that it is of lesser electrical resistance (factor 2-3) compared to a metal paste. (See, for example, the specification on page 8, line 26-page 9, line 16). That is, Nishikawa fails to disclose at least one layer comprising a metal foil to form an electrical conductor, as required by the claimed invention. This being the case, claim 9 is patentable. Claims 10-13, 15-16 and 18-20, depending either directly or indirectly from claim 9, are similarly patentable.

Claims 9, 14, 15 and 20 have been rejected under 35 USC 102(b) as anticipated by Gurkovich (U.S. Patent No. 5,769,987). The rejection is respectfully traversed. The rejection to claim 14 is moot.

Gurkovich discloses a fabrication method for integrating passive devices such as capacitors, resistors and circulators into ceramic packages for electronic systems. Gurkovich discloses two methods of integration of dielectric and passive multilayer stacks using a bonding layer approach. In neither case does Gurkovich disclose the use of at least one metal foil to form an electrical conductor. Rather, Gurkovich discloses use of passive layers and electrically

insulating bonding layers, as described in the preferred post-firing method. Hence, the applied prior art fails to disclose the features of claim 9. Claim 9 being patentable, all claims depending therefrom are similarly patentable.

Claim 10 has been rejected under 35 USC 103(a) as unpatentable over Nishikawa, further in view of Polinski (U.S. Patent No. 5,708,570). The rejection is respectfully traversed for the same reasons presented above with respect to claim 9. Additionally, Polinski fails to disclose use of a metal foil as a layer to form an electrical conductor.

Claim 11 has been rejected under 35 USC 103(a) as unpatentable over Nishikawa. The rejection is respectfully traversed for the same reasons presented above with respect to claim 9, and for the following reason. The Examiner may not make conclusory statement of obvious without presenting evidence of record in support thereof. Moreover, the Examiner fails to state a reason why one having ordinary skill in the art would have been motivated to modify the reference. Therefore, Applicants respectfully request that the Examiner cite a reference in support of his/her conclusions of obviousness, and state a reason why the skilled artisan would have been motivated to combine them.

In view of the foregoing, claims 9-13, 15-16 and 18-20 are in condition for allowance. An indication of the same is solicited.

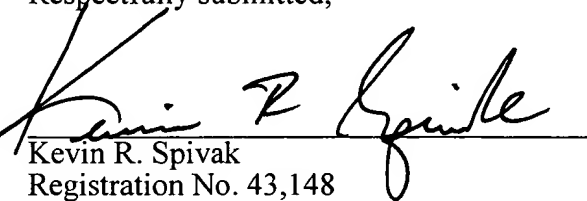
Attached hereto is a marked-up version of the changes made to the specification and claims by the current amendment. The attached page is captioned “**Version with markings to show changes made**”.

In the unlikely event that the transmittal letter is separated from this document and the Patent Office determines that an extension and/or other relief is required, Applicant petitions for any required relief including extensions of time and authorizes the Assistant Commissioner to charge the cost of such petitions and/or other fees due in connection with the filing of this document to **Deposit Account No. 03-1952** referencing docket no. 449122019100.

Respectfully submitted,

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**VERSION WITH MARKINGS TO SHOW CHANGES MADE**

**In the Claims:**

Please cancel claim 14.

Please amend the claims as follows.

9. (Amended) ~~Ceramic~~ A ceramic body ~~comprising~~ having a monolithic multilayer structure,  
comprising: containing  
-at least one passive electronic module;  
-at least one layer ~~composed of~~ comprising a first ceramic material made of glass ceramic, which becomes compacted in a first temperature interval; ~~and~~  
-at least one layer ~~composed of~~ comprising a second ceramic material made of glass ceramic, which becomes compacted at a temperature interval that is different from the first temperature interval; and  
at least one layer comprising a metal foil to form an electrical conductor.

10. (Amended) ~~Body~~ The body according to claim 9, wherein the ceramic materials exhibit ~~an~~ essentially a substantially identical coefficient of expansion at a specific temperature range.

11. (Amended) ~~Body~~ The body according to claim 9, which includes a layer stack having a layer sequence in a direction, and a layer stack having the same layer sequence in opposite direction, are arranged on top of one another.

12. (Amended) ~~Body~~ The body according to claim 9, wherein the second ceramic material becomes compacted at the temperature interval between 720 ° C and 850 ° C.

13. (Amended) ~~Body~~ The body according to claim 12, wherein the second ceramic material becomes compacted at the temperature interval between 870°C and 970°C.

15. (Amended) ~~Body~~ The body according to claim 14, wherein the body is arranged on a metal body.

16. (Amended) ~~Body~~ The body according to claim 15, wherein the at least one passive electronic module component part, the layer ~~composed of~~ comprising an electrode material and/or the metal body comprises at least one material, which is selected from the group gold, copper, molybdenum, palladium, platinum, silver and/or wolfram. {sic}

18. (Amended) ~~Body~~ The body according to claim 14, wherein the layer ~~composed of~~ comprising an electrode material comprises at least one material, which is selected from the group consisting of gold, copper molybdenum, palladium, platinum, silver and tungsten.

19. (Amended) ~~Body~~ The body according to claim 9, wherein one of the ceramic materials becomes compacted at the temperature interval between 870 °C and 970 °C.

20. (Amended) ~~Body~~ The body according to claim 9, which is a substance for a high-frequency module.